
Editorial

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Biographical notes: Leszek A. Dobrzański is Director of the Institute of Engineering Materials and Biomaterials of the SUT Gliwice, Poland, the President of World Academy of Materials and Manufacturing Engineering, a Foreign Fellow of Ukrainian and Slovak Academies of Engineering Sciences, an Editor-in-Chief of three Worldwide Journals, a Visiting Professor, an Invited Speaker, the Chairman and a Member of the Programme Committees of the serial Scientific Conferences in numerous of world countries. An author or a co-author of ca.1000 publications, ca.40 patents, ca.40 scientific books. A laureate of numerous scientific distinctions, including William Johnson and Albert Schweitzer Gold Medals with interests including broad range of materials science and materials engineering, machine design and operating, manufacturing engineering, surface engineering and engineering education.

The year 2007 was the first year of the publication of *International Journal of Computational Materials Science and Surface Engineering (IJCMSSE)*. This journal is published under the patronage of the World Academy of Materials and Manufacturing Engineering and the Association of Computational Materials Science and Surface Engineering. Its publisher is Inderscience Enterprises Ltd. which is experienced and has achievements in the publication of the journal fulfilling high programme and editorial requirements. The Publisher of *IJCMSSE* secures the worldwide range and broad distribution regularly sending it to scientific libraries and individual readers in many countries of the world. The papers published in the journal are also available in the internet in the form of abstracts, which is surely conducive to the popularisation of the contents published among the broad circles of readers.

The scope of the *IJCMSSE* includes original scientific papers which describe computer-aided methods of modelling, simulation and prediction for designing new engineering materials and the technological processes of the manufacturing, processing and forming of their structure and properties in the whole volume and their surface and also the description of phenomena and phase transformations appearing in those materials.

The journal has an ambition to create the conditions of scientific integration and the possibility of the presentation of scientific achievements on the international arena and fulfilling at the same time an education mission by promotion of the newest scientific achievements for authors and readers. *IJCMSSE* publishes papers after selection and positive review processes made by at least 2–3 reviewers each and after detailed revisions made according to reviewers' remarks and suggestions. The Editorial Board

consists of 41 outstanding professors from many countries of all continents who are responsible for reviewing and the content-related level to which the published papers belong. Furthermore, the associate editors are staff of the Institute of Engineering Materials and Biomaterials of the Silesian University of Technology in Gliwice also fulfilling editorial functions. Two experienced translators are responsible for the language of the journal which is entirely published in English. This year, *IJCMSSE* has been published in 1 volume consisting of six consecutive issues. The 2007 annual of the journal includes 50 papers and altogether 750 pages consisting of 16 editorial pages, and of the remaining 732 pages, 50 full-text and reviewed papers were published. The team of authors and co-authors of the given papers counts as many as 170 persons coming from 13 countries, such as: Canada, China, Czech Republic, Estonia, France, Greece, India, Italy, Japan, Korea, Poland, Slovenia and the USA.

The scope of the papers published in 2007 in the journal was divided into a few divisions. The most broadly represented one during this year dealt with the methods of analysis and modelling (25 papers), manufacturing and processing of engineering materials (13 papers), engineering materials (8 papers), engineering materials properties (4 papers).

The published papers dealt with current and essential issues in the field of computer-aided methods of modelling, simulation and prediction for designing engineering materials (metallic alloys, tool materials, superplastic materials, ceramics and glasses, composites, amorphous materials, nanomaterials, biomaterials, multifunctional and smart materials and engineering polymers) and their processing technologies and surface engineering.

I would like to kindly thank all the authors and other persons who contributed to the publication of the current annual of the journal for their efforts. I am convinced that the work of all the authors and also the whole editorial team and editorial board brought good results and the opinion that the level of published papers is high, that they have a very attractive graphic form and that the journal belonged to the group of important editorial events in the world is shared in many places. I hope that by further active cooperation of authors, friends of the journal and numerous teams of reviewers, members of editorial bodies, team of graphics and printers, we will manage to achieve aims in order to fulfil important scientific information and integration mission by our journal in the field of materials and manufacturing engineering in the international scientific society. Handing the given issue to P.T. readers, I hope that *IJCMSSE* is accepted by them and also by P.T. authors which guarantees the development of the journal in the future and I also wish those two groups and all other persons who sacrifice their time and talents to the publication of the future issues and volumes of the journal, wonderful successes in the future and further scientific achievements and at the same time encouraging their publication in our journal, beginning from the first, January Issue dated 2008. I do hope that the next year 2008 will bring further development and successes for the journal.